REVISIONS		
REV	DESCRIPTION	DATE
C	INCREASED DAP SIZE, REDUCED GROUND RING WIDTH	07/24/17

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CUSTOMER: xxxxx	DOCUMENT #:
PROJECT NAME: xxxxx	DIE ATTACH PAD SIZE: 1.90 x 1.90 mm
DIE SIZE, mm: xxxxx	EXPOSED PAD SIZE: 1.65 x 1.65 mm
DIE THICKNESS, um: xxxxx	DAP PLATING OPTION: GROUND RING
BOND PAD PITCH, um: xxxxx	PLATING MATERIAL: NiPdAu
BOND PAD OPENING, um: xxxxx	LEADFRAME MATERIAL: C194 FH
WIRE SIZE, um: xxxxx	LEADFRAME THICKNESS: 0.203±0.0075 mm

PROMEX INDUSTRIES INC.
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TITLE
QFN 16L 3x3 mm 0.50 PITCH BOND SHELL

LEADFRAME P/N: 235-00050			REV 00
DO NOT SCALE	FILE NAME 16L-QFN-3X3-50P-BD.DWG	SHEET 1 OF 1	